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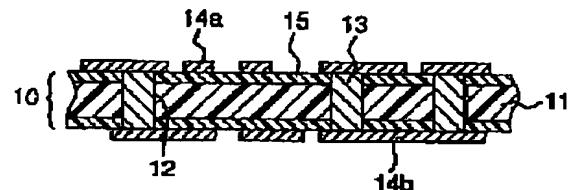
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APPLICANT : MATSUSHITA ELECTRIC IND CO LTD;

INVENTOR : HASEGAWA MASAO;

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TITLE : CIRCUIT BOARD AND ITS
MANUFACTURE



ABSTRACT : PROBLEM TO BE SOLVED: To mount components in a high density by electrically connecting predetermined wiring patterns of both sides of an insulation base plate via a conductive material filled in a through hole of the plate made of a heat insulation film disposed on resin-impregnated fiber sheet and at least at one side of the sheet.

SOLUTION: Heat resistant resin films 16 substantially having no compatibility with resin-impregnated fiber sheet 11 obtained by impregnating nonwoven fabric of organic fiber with thermosetting resin are disposed on both side surfaces of the sheet 11 to constitute composite material as an insulation base plate 10. At least one through hole 12 is provided at a predetermined position of the plate 10, and conductive material 13 is filled in the hole. Predetermined wiring patterns 14a, 14b are formed on heat resistant films 15 for constituting both sides of the plate 10, and electrically connected by the material 13. Thus, a fine wiring pattern can be accurately formed.

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